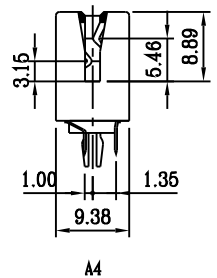
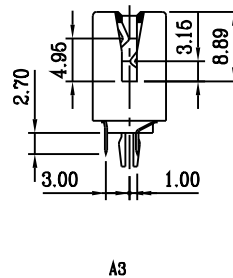
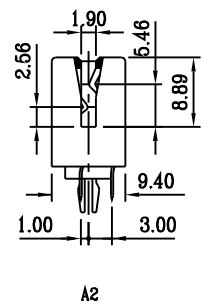
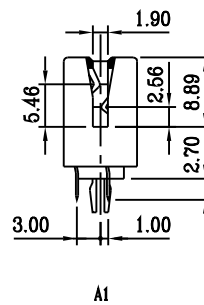
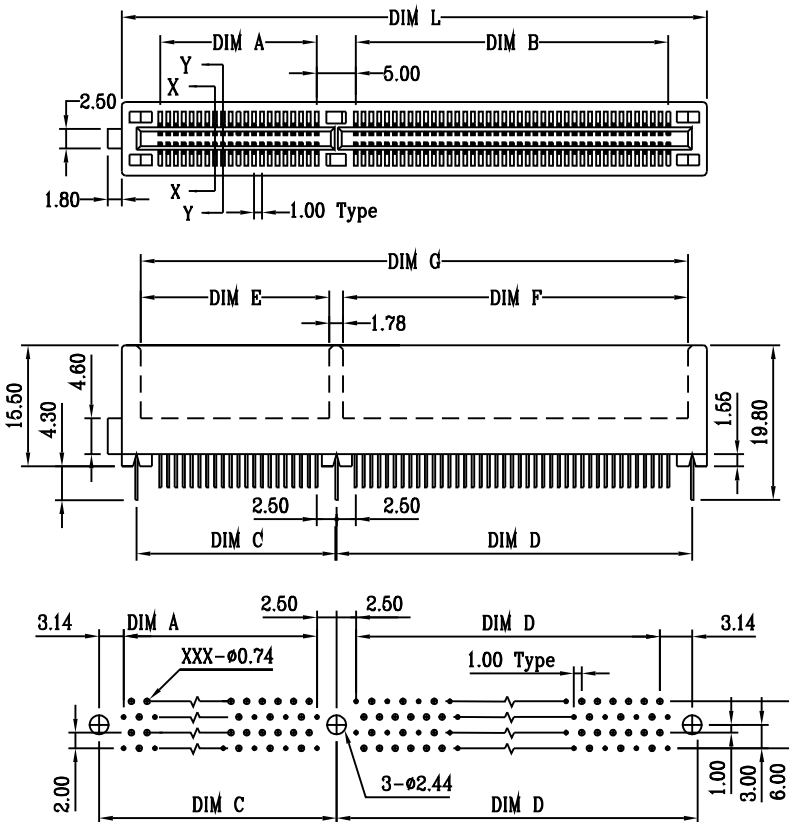
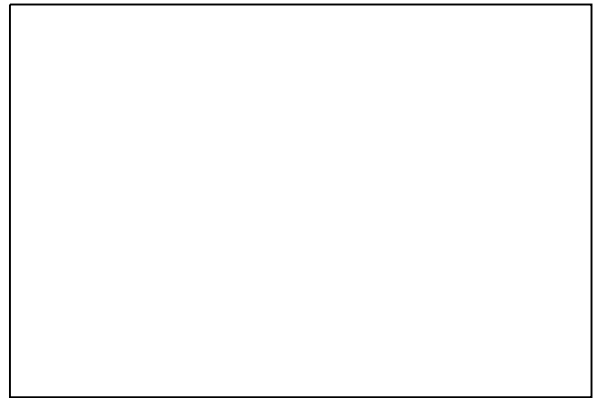


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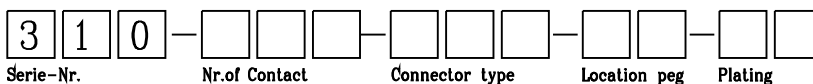
High-Density Edge Card Connector Pitch 1.0mm AGP & SLOT 1

Technical data :

Body : High temperature thermoplastic, UL 94v-0
 Contacts : Copper alloy
 Contact Plating : Gold plating over nickel on contact
 area Tin/Lead plating on terminal
 Insertion Force : 100 Grams max.
 Withdrawal Force : 30 Grams min.
 Contact Retention : 350 Grams min.
 Contact Resistance : 10 Milliohms max. initial ,
 2 Milliohms Max. Increase Through Testing.
 Current Rating : 1 Ampere.
 Insulation Resistance : 1000 Megohms min.
 Dielectric Withstanding Voltage : 500 VAC. 1 minute.
 Capacitance : 2 pf max.



How to order



	Contact Per Row	Bay A	Bay B	Dimensions(mm)											Cold
				A	B	C	D	E	F	G	H	I	L		
AGP	62/124	21/42	41/82	20.00	40.00	24.64	45.64	23.64	43.64	69.05	24.00	44.00	73.88	124	
SLOT 1	121/242	73/146	48/96	72.00	47.00	77.64	52.64	75.64	60.64	128.05	76.00	51.00	132.88	242	

Plating option	Cod
Flash selective good plated	60
5u" selective good plated	05
10u" selective good plated	10
Flash good over 15u" Palladium	15
Flash good over 20u" Palladium	20
Flash good over 30u" Palladium	30

Connector type	Code
Loose contact A1	101
Loose contact A2	102
Stamped Form contact A3	201
Stamped Form contact A4	202

Location peg	Code
W/O Location peg	00
W/ Metal peg	10